

AIM 40Bi/60Sn Solder for Photonic Packaging

Category : Metal , Nonferrous Metal , Bismuth Alloy , Solder/Braze Alloy , Tin Alloy

Material Notes:

Uses include:Fiber to Ferrule SolderingLaser Die AttachHermetic Packaging & SealingWetting & Sealing Laser OpticsThermal ManagementInformation provided by AIM Specialty Materials.

Order this product through the following link:

http://www.lookpolymers.com/polymer_AIM-40Bi60Sn-Solder-for-Photonic-Packaging.php

Physical Properties	Metric	English	Comments
Density	8.12 g/cc	0.293 lb/in ³	

Thermal Properties	Metric	English	Comments
CTE, linear	14.0 $\mu\text{m}/\text{m}\cdot\text{°C}$	7.78 $\mu\text{in}/\text{in}\cdot\text{°F}$	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Melting Point	138 - 170 °C	280 - 338 °F	
Solidus	138 °C	280 °F	
Liquidus	170 °C	338 °F	

Component Elements Properties	Metric	English	Comments
Bismuth, Bi	40 %	40 %	
Tin, Sn	60 %	60 %	

Descriptive Properties	Value	Comments
Creep Resistance	Moderate	

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